RELIABILITY REPORT

FOR

MAX8792ETD+

PLASTIC ENCAPSULATED DEVICES

December 23, 2008

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX8792ETD+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX8792 pulse-width modulation (PWM) controller provides high efficiency, excellent transient response, and high DC-output accuracy needed for stepping down high-voltage batteries to generate low-voltage core or chipset/RAM bias supplies in notebook computers. The output voltage can be dynamically controlled using the dynamic REFIN, which supports input voltages between 0 to 2V. The REFIN adjustability combined with a resistive voltage-divider on the feedback input allows the MAX8792 to be configured for any output voltage between 0 to 0.9 VIN. Maxim's proprietary Quick-PWM(tm) quick-response, constant-on-time PWM control scheme handles wide input/output voltage ratios (low-duty-cycle applications) with ease and provides 100ns "instant-on" response to load transients while maintaining a relatively constant switching frequency. Strong drivers allow the MAX8792 to efficiently drive large synchronous-rectifier MOSFETs. The controller senses the current across the synchronous rectifier to achieve a low-cost and highly efficient valley current-limit protection. The adjustable current-limit threshold provides a high degree of flexibility, allowing thermally compensated protection using an NTC or foldback current-limit protection using a voltage-divider derived from the output. The MAX8792 includes a voltage-controlled soft-start and soft-shutdown in order to limit the input surge current, provide a monotonic power-up (even into a precharged output), and provide a predictable powerup time. The controller also includes output fault protection- undervoltage and overvoltage protection-as well as thermal-fault protection. The MAX8792 is available in a tiny 14-pin, 3mm x 3mm TDFN package. For space-constrained applications, refer to the MAX17016 single step-down with 10A, 26V internal MOSFETs available in a small 40-pin, 6mm x 6mm TQFN package.

II. Manufacturing Information

A. Description/Function:	Single Quick-PWM Step-Down Controller with Dynamic REFIN
B. Process:	S4
C. Number of Device Transistors:	
D. Fabrication Location:	Texas
E. Assembly Location:	UTL Thailand
F. Date of Initial Production:	January 20, 2007

III. Packaging Information

A. Package Type:	14-pin TDFN 3x3
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2581
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	54°C/W
K. Single Layer Theta Jc:	8.3°C/W
L. Multi Layer Theta Ja:	41°C/W
M. Multi Layer Theta Jc:	8.3°C/W

IV. Die Information

A. Dimensions:	41 X 94 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 47 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.8 \times 10^{-9}$

$\lambda = 22.8$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the S4 Process results in a FIT Rate of 4.6 @ 25C and 79.2 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The PE04 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114-D. Latch-Up testing has shown that this device withstands a current of +/-100 mA and a 1.5x VCCmax Overvoltage Stress per JSTD 78.

Table 1
Reliability Evaluation Test Results

MAX8792ETD+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	47	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data